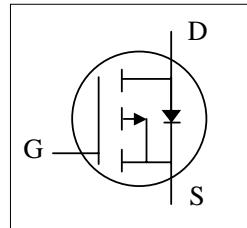




- ▼ Lower On-resistance
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free

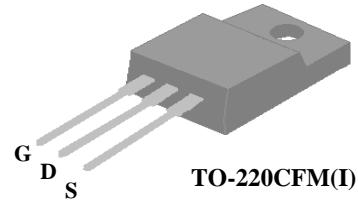


BV_{DSS}	-30V
$R_{DS(ON)}$	28mΩ
I_D	-30A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220CFM isolation package is widely preferred for all commercial-industrial through hole applications.



TO-220CFM(I)

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-30	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-18	A
I_{DM}	Pulsed Drain Current ¹	-120	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	31.3	W
	Linear Derating Factor	0.25	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-c}	Maximum Thermal Resistance, Junction-case	4	$^\circ C/W$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient	65	$^\circ C/W$



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$	-30	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $\text{I}_D=-1\text{mA}$	-	-0.02	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-18\text{A}$	-	-	28	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-10\text{A}$	-	-	50	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$	-1	-	-3	V
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-10\text{V}, \text{I}_D=-18\text{A}$	-	21	-	S
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-30\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-1	uA
	Drain-Source Leakage Current ($T_j=125^\circ\text{C}$)	$\text{V}_{\text{DS}}=-24\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-250	uA
I_{GSS}	Gate-Source Leakage	$\text{V}_{\text{GS}}= \pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$\text{I}_D=-18\text{A}$	-	15	24	nC
Q_{gs}	Gate-Source Charge	$\text{V}_{\text{DS}}=-25\text{V}$	-	3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$\text{V}_{\text{GS}}=-4.5\text{V}$	-	10	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time ²	$\text{V}_{\text{DS}}=-15\text{V}$	-	10	-	ns
t_r	Rise Time	$\text{I}_D=-18\text{A}$	-	48	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$\text{R}_G=3.3\Omega$	-	31	-	ns
t_f	Fall Time	$\text{V}_{\text{GS}}=-10\text{V}$	-	66	-	ns
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$	-	910	1460	pF
C_{oss}	Output Capacitance	$\text{V}_{\text{DS}}=-25\text{V}$	-	300	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	210	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	11	17	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$\text{I}_S=-18\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-1.3	V
t_{rr}	Reverse Recovery Time ²	$\text{I}_S=-18\text{A}, \text{V}_{\text{GS}}=0\text{V},$ $d\text{I}/dt=-100\text{A}/\mu\text{s}$	-	30	-	ns
			-	25	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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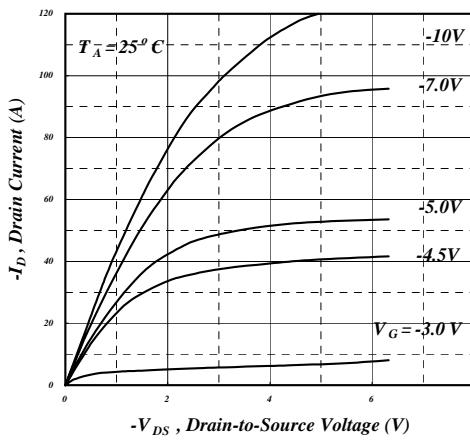


Fig 1. Typical Output Characteristics

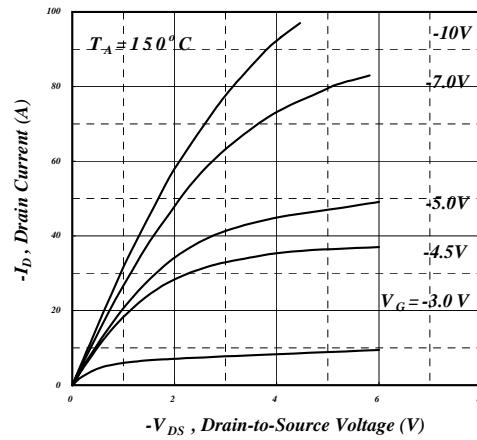


Fig 2. Typical Output Characteristics

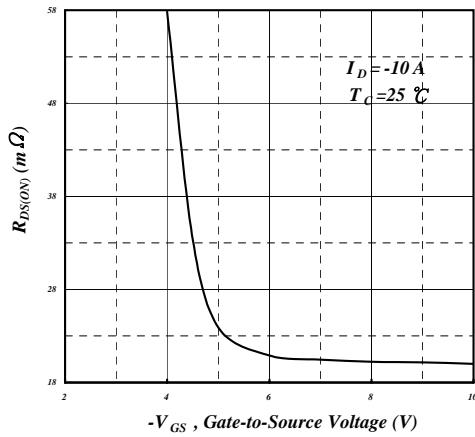


Fig 3. On-Resistance v.s. Gate Voltage

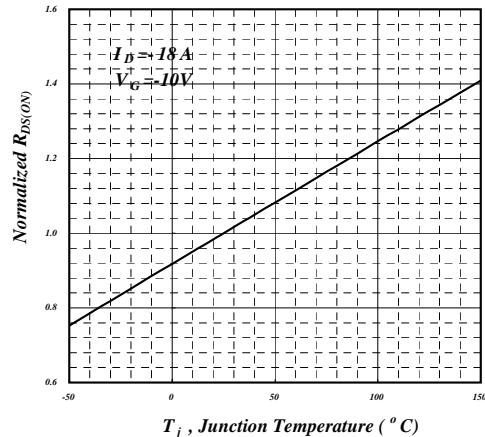


Fig 4. Normalized On-Resistance v.s. Junction Temperature

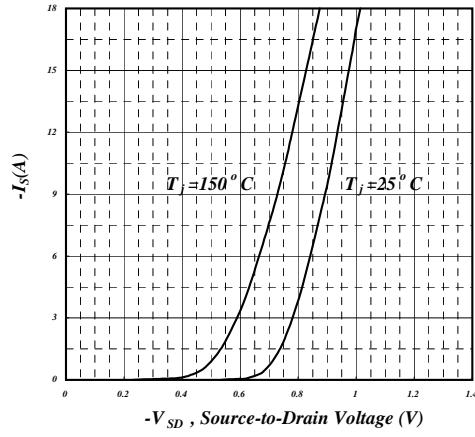


Fig 5. Forward Characteristic of Reverse Diode

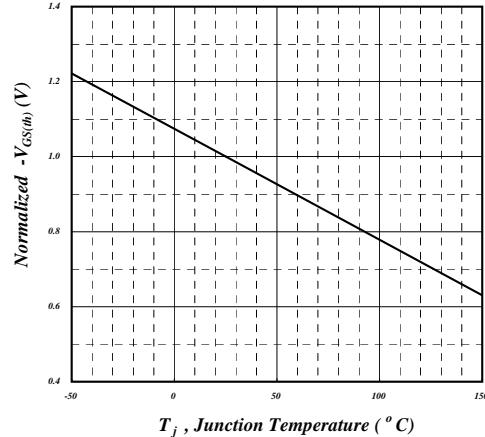


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



AP40P03GI-HF

